Product End-of-Life Disassembly Instructions

Product Category: Personal Computers

Marketing Name / Model
[List multiple models if applicable.]

- HP ProDesk 600 G1 Small Form Factor Business PC

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

### 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>2</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td></td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>Liteon EPA90</td>
<td>5</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td>1</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink including liquids, semi-liquids (gel/paste) and toner including chambers, and service stations.</td>
<td>Include the cartridges, print heads, tubes, vent</td>
<td></td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>
Components, parts and materials containing refractory ceramic fibers

Components, parts and materials containing radioactive substances

**2.0 Tools Required**

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Screwdriver</td>
<td>T-15</td>
</tr>
<tr>
<td>Micro shear</td>
<td>170II</td>
</tr>
<tr>
<td>Screwdriver</td>
<td>PH1</td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

**3.0 Product Disassembly Process**

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove the access panel.(see Figure 1 below)
2. Rotate the driver cage form the hook on slide rail.(see Figure 2 below)
3. Disconnect SATA cables from the MB.(see Figure 3 below)
4. Disconnect other PSU cables from the MB.(see Figure 4-9 below)
5. Remove HDD/ODD from chassis.(see Figure 10-16 below)
6. Remove the heatsink from MB.(see Figure17-19 below)
7. Separate the fan from CPU heatsink. (see Figure 20-21 below)
8. Remove the CPU from the MB.(see Figure 22-23 below)
9. Remove the Memory card from the MB.(see Figure 24 below)
10. Remove the battery from the MB .(see Figure 25 below)
11. Remove M/B from chassis.(see Figure 26-27 below)
12. Remove front panel from chassis.(see Figure 28 below)
13. Remove FIO/Speaker/LED holder from chassis.(see Figure 29-31 below)
14. Remove PSU cover.(see Figure 32-36 below)
15. Disconnect all the cables and remove the Electrolytic Capacitors.(see Figure 37-41 below)

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
Figure 1 Remove the access panel.

Figure 2 Rotate the driver cage from the hook on slide rail.

Figure 3 Disconnect SATA cables from the MB.

Figure 4 Disconnect FIO cables from MB.

Figure 5 Disconnect Speaker cable from the MB.

Figure 6 Disconnect ODD/HDD PSU cables from the MB.

PSG instructions for this template are available at [EL-MF877-01](#).
<table>
<thead>
<tr>
<th>Figure</th>
<th>Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>7</td>
<td>Disconnect MB PSU cable from the MB</td>
</tr>
<tr>
<td>8</td>
<td>Disconnect other PSU cables from the MB</td>
</tr>
<tr>
<td>9</td>
<td>Disconnect CPU Power cable from the MB</td>
</tr>
<tr>
<td>10</td>
<td>Disconnect HDD Power cable from the MB</td>
</tr>
<tr>
<td>11</td>
<td>Disconnect SATA cable from HDD</td>
</tr>
<tr>
<td>12</td>
<td>Remove the cables the chassis clip</td>
</tr>
</tbody>
</table>

PSG instructions for this template are available at [EL-MF877-01](#).
Figure 13 Press the HDD’s latch on HDD cage

Figure 14 Remove the HDD from cage

Figure 15 Press the ODD’s latch on ODD cage

Figure 16 Remove the ODD from cage

Figure 17 Remove the Heatsink PSU cable from MB

Figure 18 Rotate the Fan duct and remove it from chassis

PSG instructions for this template are available at EL-MF877-01
Figure 19: Loose the screws and remove heat sink

Figure 20: Loose the screws and remove heatsink fan

Figure 21: Separate the fan from CPU heatsink

Figure 22: Rotate the handle and open it up

Figure 23: Remove the CPU from the board

Figure 24: Remove the Memory card from the board

PSG instructions for this template are available at EL-MF877-01
Figure 25 Remove the battery from the system board

Figure 26 Loose the screws of MB from board

Figure 27 Remove M/B from chassis

Figure 28 Remove front panel from chassis

Figure 29 Loose the screws of FIO and remove it

Figure 30 Loose the screws of speaker and remove it

PSG instructions for this template are available at [EL-MF877-01](#)
Figure 31 Remove the holder of LED power cable from chassis

Figure 32 Remove the screws on the PSU chassis

Figure 33 Press the PSU's latch on chassis

Figure 34 Remove the Power supply from chassis

Figure 35 Remove screw for top

Figure 36 Remove screw for bottom

PSG instructions for this template are available at EL-MF877-01
Figure 37 Remove the screw and open case
Figure 38 Disconnect the cable-wire from product

Figure 39 When removed only PCBA left
Figure 40 Remove Ele-Cap from PCBA

Figure 41 Show Ele-Cap on PCBA

PSG instructions for this template are available at EL-MF877-01